# 1.5V Drive Pch MOSFET

## **RZR025P01**

### Features

- 1) Low On-resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small and Surface Mount Package (TSMT3).
- 4) Low voltage drive (1.5V).

### Application

Switching

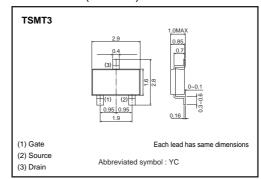
### Structure

Silicon P-channel MOSFET

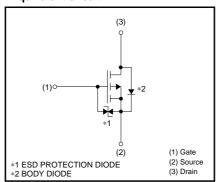
### Packaging specifications

	Package	Taping	
Type	Code	TL	
	Basic ordering unit (pieces)	3000	
RZR025P01	0		

### ●Dimensions (Unit:mm)



### ●Equivalent circuit



### ● Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit		
Drain-source voltage		V <sub>DSS</sub>	-12	V		
Gate-source voltage		V <sub>GSS</sub>	±10	V		
Drain augrant	Continuous	I <sub>D</sub>	±2.5	Α		
Drain current	Pulsed	I <sub>DP</sub> *1	±10	Α		
Source current	Continuous	Is	-0.8	Α		
(Body diode)	Pulsed	I <sub>SP</sub> *1	-10	Α		
Total power dissipation		P <sub>D</sub> *2	1.0	W		
Channel temperature		Tch	150	°C		
Range of Storage temperature		Tstg	-55 to +150	°C		
·						

<sup>\*1</sup> Pw≤10µs, Duty cycle≤1% \*2 Mounted on a ceramic board

### ●Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	Rth (ch-a) *	125	°C / W

<sup>\*</sup> When mounted on a ceramic board.

### ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	I <sub>GSS</sub>	-	-	±10	μА	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V
Drain-source breakdown voltage	V <sub>(BR)</sub> DSS	-12	_	_	٧	I <sub>D</sub> = -1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	IDSS	-	_	-1	μΑ	V <sub>DS</sub> = -12V, V <sub>GS</sub> =0V
Gate threshold voltage	VGS (th)	-0.3	_	-1.0	٧	Vps= -6V, Ip= -1mA
	R <sub>DS (on)</sub> *	-	44	61	mΩ	I <sub>D</sub> = -2.5A, V <sub>G</sub> S= -4.5V
Static drain-source on-state		_	60	84	mΩ	I <sub>D</sub> = -1.2A, V <sub>G</sub> S= -2.5V
resistance		-	81	121	mΩ	I <sub>D</sub> = -1.2A, V <sub>G</sub> S= -1.8V
		-	110	220	mΩ	I <sub>D</sub> = -0.5A, V <sub>G</sub> s= -1.5V
Forward transfer admittance	Y <sub>fs</sub>   *	3.5	-	-	S	V <sub>DS</sub> = -6V, I <sub>D</sub> = -2.5A
Input capacitance	Ciss	_	1350	_	pF	V <sub>DS</sub> = -6V
Output capacitance	Coss	_	130	_	pF	V <sub>GS</sub> =0V
Reverse transfer capacitance	Crss	-	125	_	pF	f=1MHz
Turn-on delay time	<b>t</b> d (on) *	-	9	_	ns	I <sub>D</sub> = -1.2A
Rise time	tr *	_	35	_	ns	VDD≒-6V
Turn-off delay time	t <sub>d (off)</sub> *	_	130	_	ns	$V_{GS} = -4.5V$ $R_{L} = 5\Omega$
Fall time	t <sub>f</sub> *	_	85	-	ns	R <sub>G</sub> =10Ω
Total gate charge	Q <sub>g</sub> *	_	13	-	nC	V <sub>DD</sub> ≒-6V, I <sub>D</sub> =-2.5A
Gate-source charge	Qgs *	_	2.5	-	nC	Vgs= -4.5V
Gate-drain charge	Q <sub>gd</sub> *	_	2.0	-	nC	$R_L = 2.4\Omega$ , $R_G=10\Omega$

<sup>\*</sup>Pulsed

### ●Body diode characteristics(Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	V <sub>SD</sub> *	_	_	-1.2	V	I <sub>S</sub> = -2.5A, V <sub>GS</sub> =0V

<sup>\*</sup> Pulsed

### •Electrical characteristic curves

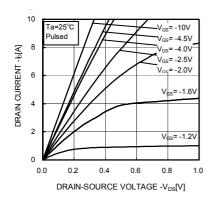


Fig.1 Typical Output Characteristics( I )

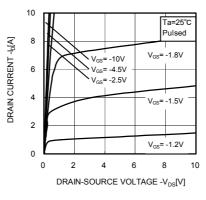


Fig.2 Typical Output Characteristics(  ${\rm I\hspace{-.1em}I}$  )

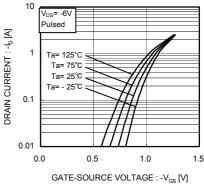


Fig.3 Typical Transfer Characteristics

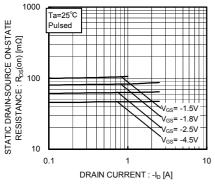


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current( I )

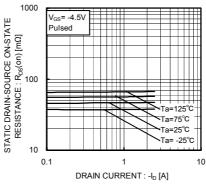


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current( ■)

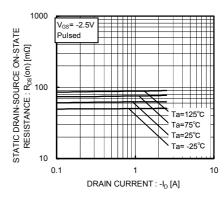


Fig.6 Static Drain-Source On-State
Resistance vs. Drain Current(Ⅲ)

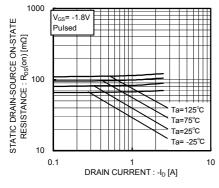


Fig.7 Static Drain-Source On-State
Resistance vs. Drain Current(IV)

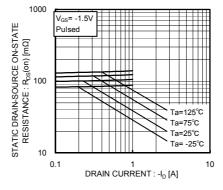


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current(IV)

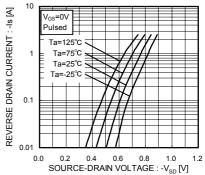


Fig.9 Reverse Drain Current vs. Sourse-Drain Voltage

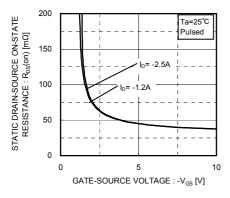


Fig.10 Static Drain-Source On-State
Resistance vs. Gate Source Voltage

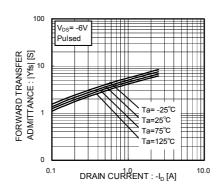


Fig.11 Forward Transfer Admittance vs. Drain Current

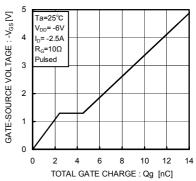


Fig.12 Dynamic Input Characteristics

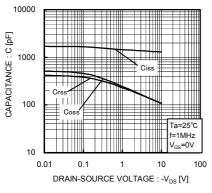


Fig.13 Typical Capacitance vs. Drain-Source Voltage

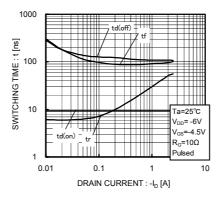


Fig.14 Switching Characteristics

### ●Measurement circuits

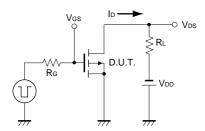


Fig.15 Switching Time Test Circuit

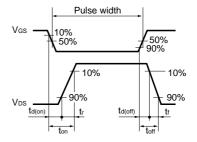


Fig.16 Switching Time Waveforms

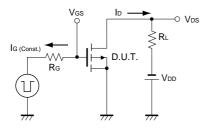


Fig.17 Gate Charge Test Circuit

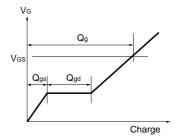


Fig.18 Gate Charge Waveform

### ●Notice

This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

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